Liquid Gap Filler Potting Compound CTLCF200Y

Thermal conductive potting compound is a low-viscosity two-component silicone potting material. This product has good fluidity, does not produce small molecules during curing, has excellent thermal conductivity and insulation properties after curing, and has no corrosion to various substrates. It is mainly used for potting of electronic components and circuit boards, such as driving power supplies. Sensors, photovoltaic junction boxes, etc., provide protection for electrical / electronic devices components under severe conditions such as high humidity, extreme temperature, thermal cycle stress, mechanical shock and vibration, mold, dirt, etc., no contact thermal resistance, seamless contact Heat-generating electronic components, heat is conducted from the separation device or the entire PCB to the metal shell or diffusion plate, thereby improving the efficiency and service life of the heat-generating electronic components.



Product Features

- High thermal conductivity, low viscosity.
- Good fluidity and rapid defoaming.
- Curing at room temperature, heating can speed up the curing speed.
- No corrosion to the substrate.

Typical Applications

- Potting protection for power modules, inverters and ballasts.
- Potting protection of electronic control unit and sensors.
- Potting protection of LED lighting components.
- Potting applications for other suitable products.

Electrically Insulating, Thermally Conductive Potting Material

TYPICAL PROPERTIES OF POTTING COMPOUND CTLCF200Y			
Test Item	CTLCF200Y		Test Method
	A Part	B Part	
Appearance	White	Grey	Visual
adhesion	10000±500	10000±500	ASTM D3116
Mixing Ratio	1:1		/
Performance After Mixing			
Adhesion	10000mPa·s/25℃		ASTM E3116
Operable Time	60min/25℃		ASTM C679
Curing Time	480min/25℃		/
Properties After Curing			
Appearance	Gray Solid		Visual
Thermal Conductivity	2.0±0.20 W/mk		ISO22007
Hardness	50±5 Shore A		ASTM D2240
Specific Gravity	2.70g/cm³±0.05		ASTM D792
Tensile Strength	0.85MPa		ASTM D412
Volume Resistivity	1x10 ¹³ Ω·cm		ASTM D257
Breakdown Voltage	>15KV/mm		ASTM D149
Dielectric Constant	4.2(@1MHz)		ASTM D150
Linear Expansion Coefficient	124 μm/(m·℃)		ASTM E228
Flame Rating	V-0		UL94
Continuous Use Temp	-40~200 °C		/
Specific Heat Capacity	0.964 J/(g*k)		ASTM D1269

Packaging: components a and B are packed in independent plastic drums, and the package specification is 25kg / 25kg.

Storage: it shall be stored in a cool and dry place without direct sunlight. It is recommended that the storage temperature be lower than 27 $^{\circ}$ C. It can be stored for 6 months from the production date when it is unopened and well sealed. During storage, the filler may settle, which is normal. It should be mixed evenly before use.

Build a Part Number Standard Options



Note: The material can be customized. If you can't find the material that meets your requirements in our existing materials, you can consult the sales manager whether the material you need supports customization, and we will give you a reply within 24H.

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